2SD0637 (2SD637)

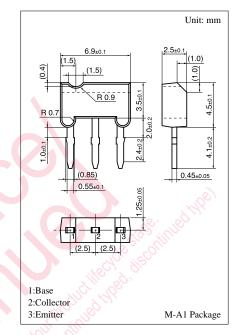
Silicon NPN epitaxial planer type

For low-power general amplification

Features

- High foward current transfer ratio h_{FE}.
- Low collector to emitter saturation voltage V_{CE(sat)}.
- M type package allowing easy automatic and manual insertion as well as stand-alone fixing to the printed circuit board.

	•		
Parameter	Symbol	Ratings	Unit
Collector to base voltage	V _{CBO}	60	V
Collector to emitter voltage	V _{CEO}	50	V
Emitter to base voltage	V _{EBO}	7	V
Peak collector current	I _{CP}	200	mA
Collector current	I _C	100	mA
Collector power dissipation	P _C	400	mW
Junction temperature	Tj	150	°C
Storage temperature	T _{stg}	-55 ~ +150	°C



Absolute Maximum Ratings (Ta=25°C)

Electrical Characteristics (Ta=25°C)

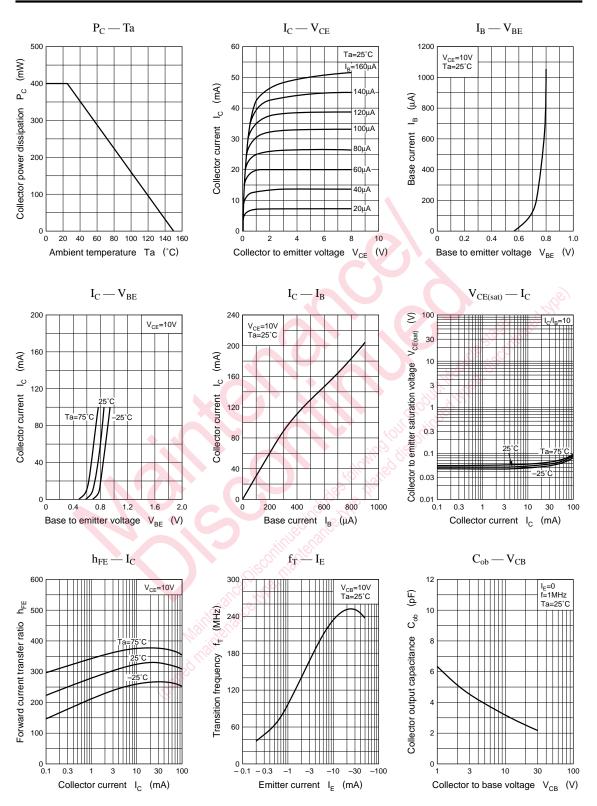
Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I _{CBO}	$V_{CB} = 20V, I_E = 0$			1	μΑ
	I _{CEO}	$V_{CE} = 20V, I_B = 0$			1	μΑ
Collector to base voltage	V _{CBO}	$I_{\rm C} = 10 \mu A, I_{\rm E} = 0$	60			v
Collector to emitter voltage	V _{CEO}	$I_{\rm C} = 2{\rm mA}, I_{\rm B} = 0$	50			v
Emitter to base voltage	VEBO	$I_{\rm E} = 10 \mu A, I_{\rm C} = 0$	7			v
Forward current transfer ratio	h _{FE} *	$V_{CE} = 10V$, $I_C = 2mA$	160		460	
Collector to emitter saturation voltage	V _{CE(sat)}	$I_{C} = 100 \text{mA}, I_{B} = 10 \text{mA}$		0.3	0.5	V
Transition frequency	f _T	$V_{CB} = 10V, I_E = -2mA, f = 200MHz$		150		MHz
Collector output capacitance	C _{ob}	$V_{CB} = 10V, I_E = 0, f = 1MHz$		3.5		pF

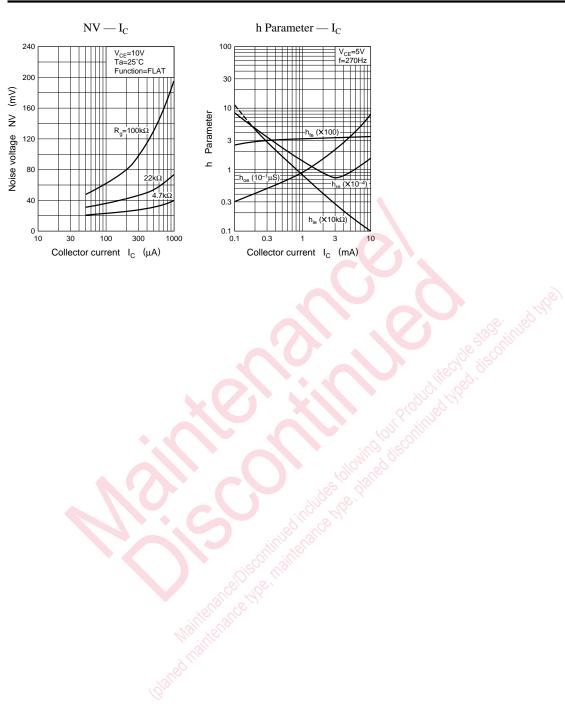
*hFE Rank classification

Rank	Q	R	S
h _{FE}	160 ~ 260	210 ~ 340	290 ~ 460

Note.) The Part number in the Parenthesis shows conventional part number.

Transistor





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